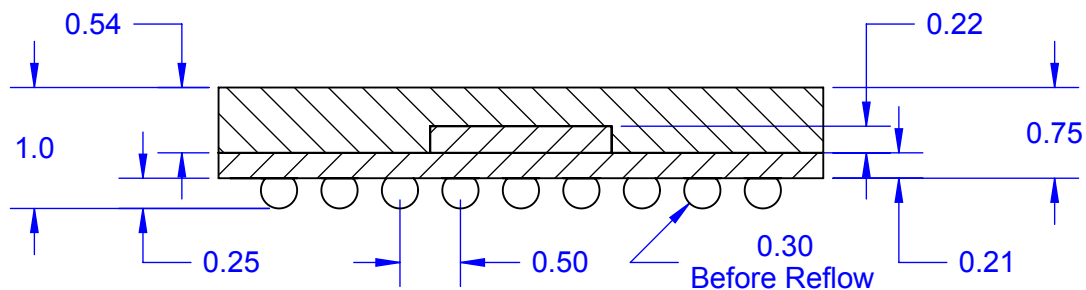
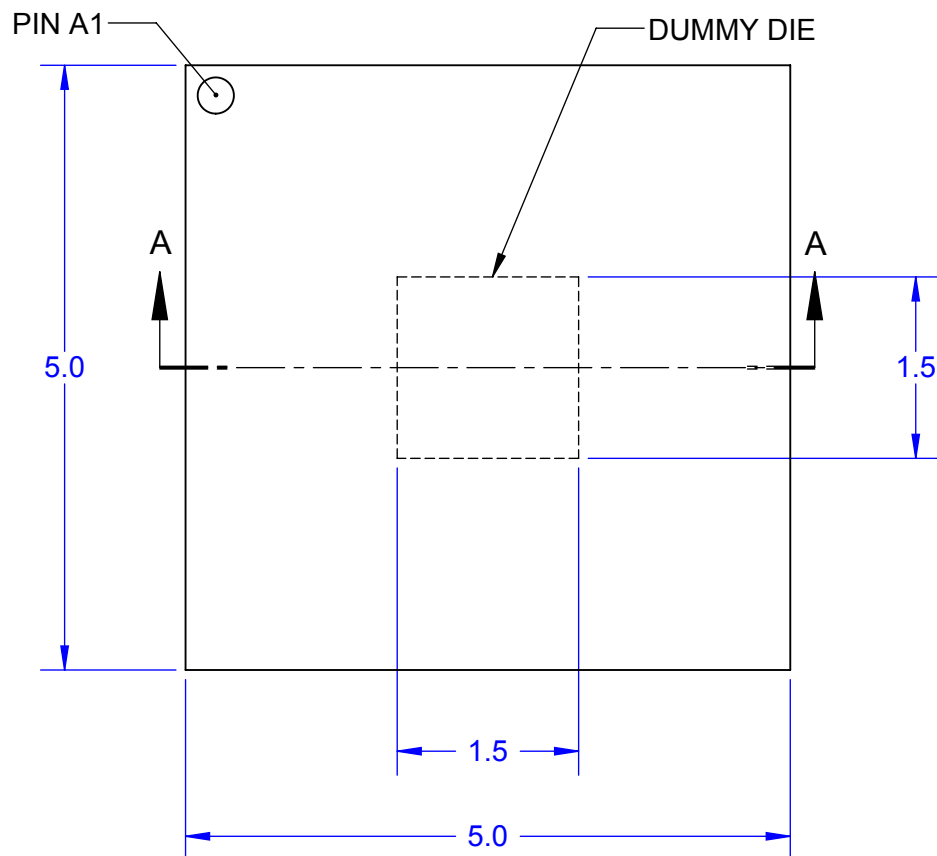
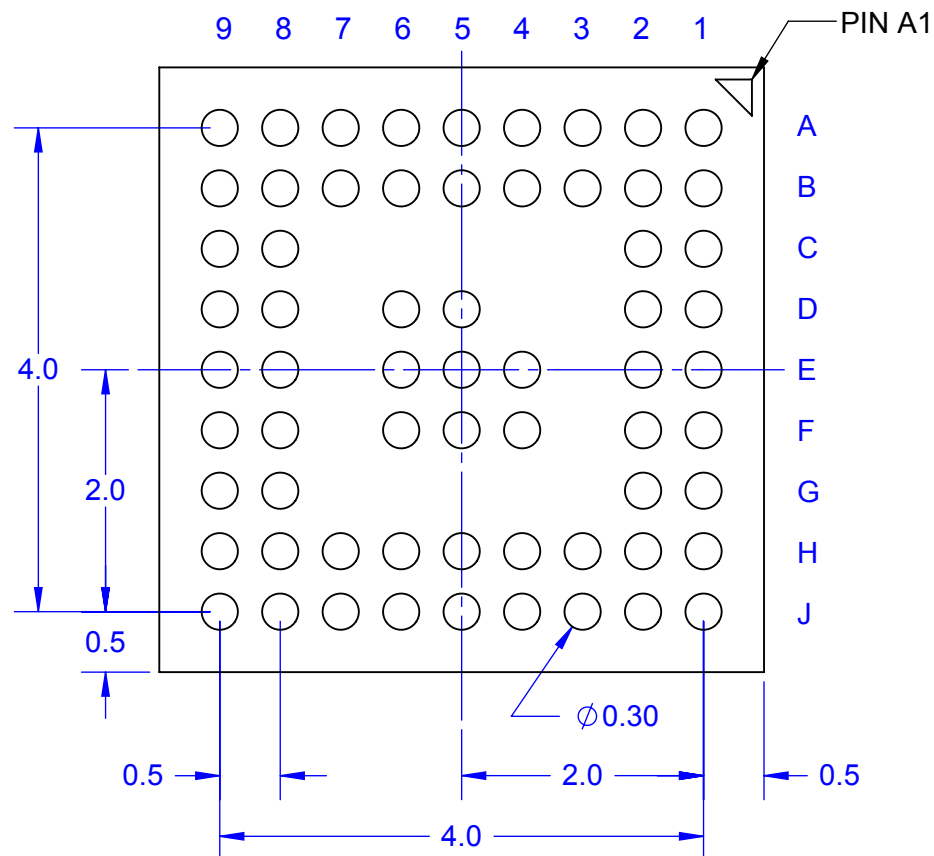


TOP VIEW



SECTION A-A

BALL VIEW

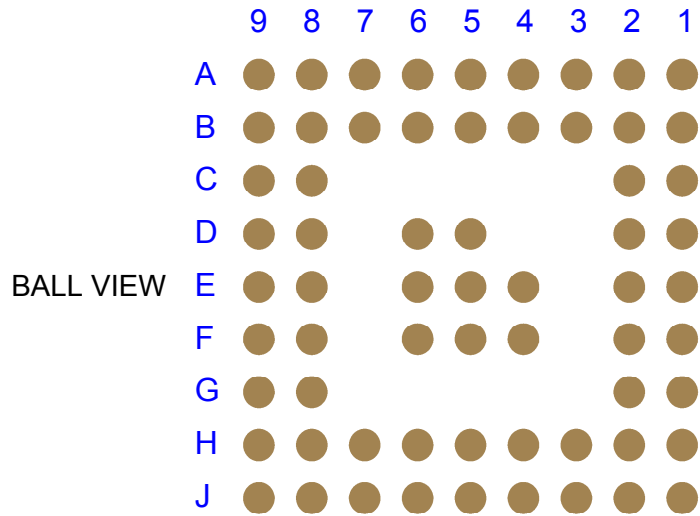


Notes: (Unless Otherwise Specified).

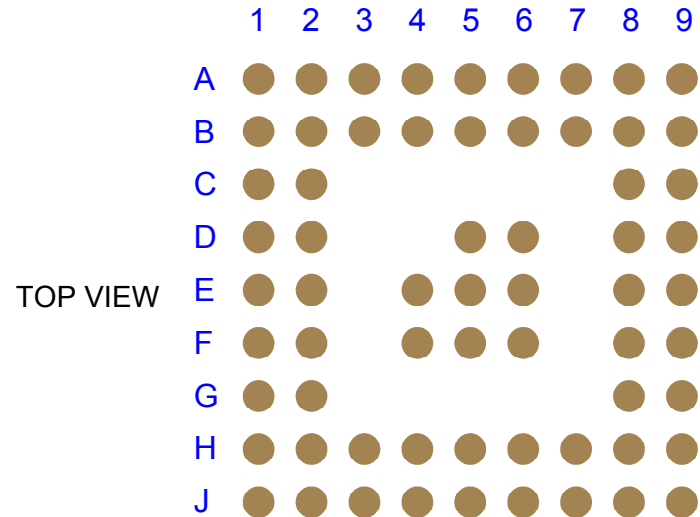
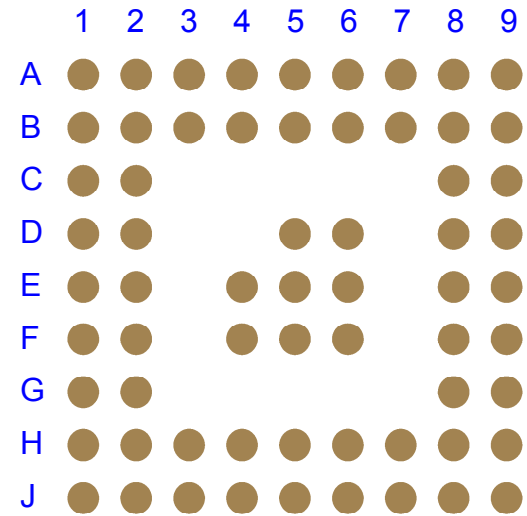
- 1) ALL DIMENSIONS ARE IN MM.
- 2) SOLDER BALL ALLOY: SEE PART NUMBER TABLE.
- 3) BALL DIAMETER (BEFORE REFLOW): 0.30mm.
- 4) SOLDER MASK DEFINED PAD OPENING: 0.254mm [10 MIL].
- 5) PAD Cu DIAMETER: 0.30mm [12 MIL].
- 6) SUBSTRATE MATERIAL: BT.
- 7) MSL-3 RECOMMEND BAKING 24 HOURS @ 125C TO REMOVE MOISTURE PRIOR TO SOLDERING TO PC BOARD.

PART NUMBER TABLE					
PART NUMER	BALL ALLOY	Pb-FREE	RoHS	Si DIE	Pack
BGA64T.5C-9x9-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES	TRAY
BGA64E13A.5C-9x9-D	Sn96.5/Ag3.0/Cu0.5	YES	YES	YES	REEL

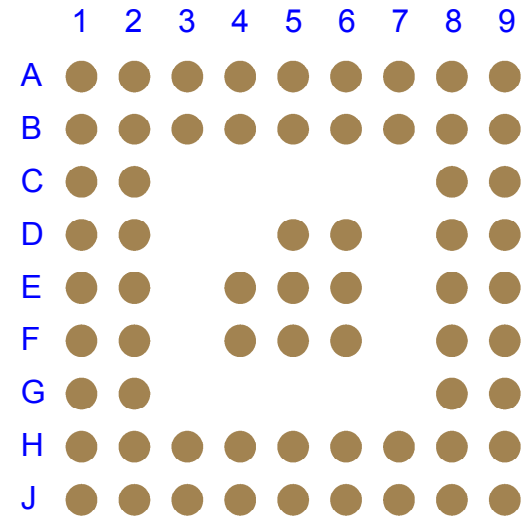
APPROVALS	DATE				
DRAWN T.Au	04/22/14				
ENG M. Hart	04/22/14	TITLE BGA64T.5C-9x9-D DAISY CHAIN DUMMY			
MFG					
QA		SCALE 15:1	SIZE A	DRAWING NO. 550920	REV A
CUST					
REVISED		DO NOT SCALE DRAWING			
					SHEET 1 OF 2



BOTTOM SIDE
(TOP X-RAY VIEW)



AFTER MOUNTING
TO TEST BOARD
(TOP X-RAY VIEW)



Notes:

- 1) PCB BOARD DIMENSIONS ARE PRESENTED ONLY AS A GUIDELINE.
DESIGNERS SHOULD USE THEIR OWN EXPERIENCE WHEN DESIGNING PCB.
- 2) PCB Cu BALL PAD DIAMETER 0.30mm [12 MIL].
- 3) SMD (SOLDER MASK DEFINED) PAD OPENING 0.254mm [10 MIL].

TopLine[®]

TITLE BGA64T.5C-9x9-D
DAISY CHAIN DUMMY

SCALE 14:1	SIZE A	DRAWING NO. 550920	REV A
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DO NOT SCALE DRAWING

SHEET 2 OF 2